









PRODUCT DATASHEET



- ► PLCC2 Top View SMD
- ▶ 3020 1.3t
- ➤ Yellow 590nm

N0Y03S28





3020 1.3t Series





FEATURES:

Package: PLCC2 Single Colour Top View SMD

Forward Current: 20mA Forward Voltage (typ.): 2.0V

Luminous Intensity (typ.): 800mcd@20mA

Colour: Yellow

Wavelength: 585~597nm Viewing angle: 120°

Materials:

Die: AlGaInP

Resin: Silicone (Water Clear)

Finishing: Ag plated

Operating Temperature: -40~+80°C Storage Temperature: -40~+100°C

ESD (HBM): 2KV

Grouping parameters:

Forward voltage

Luminous intensity

Dominant wavelength

Soldering methods: Reflow

MSL: acc. to JEDEC Level 2a

Packing: 8mm tape with max.3000/reel, ø180mm (7")

APPLICATIONS:

- Backlighting
- Indication Light
- Switch light
- Dashboard
- **Decoration Lighting**



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	IF	50	mA
Peak Forward Current Duty 1/10; width 0.1ms	I _{FP}	100	mA
Reverse Voltage	VR	8	V
Reverse Current @8V	I _R	10	μА
Junction Temperature	Tj	110	°C
Operating Temperature	T _{OPR}	-40~+80	°C
Storage Temperature	T_{STG}	-40~+100	°C

Electrical & Optical Characteristics (Ta=25°C)

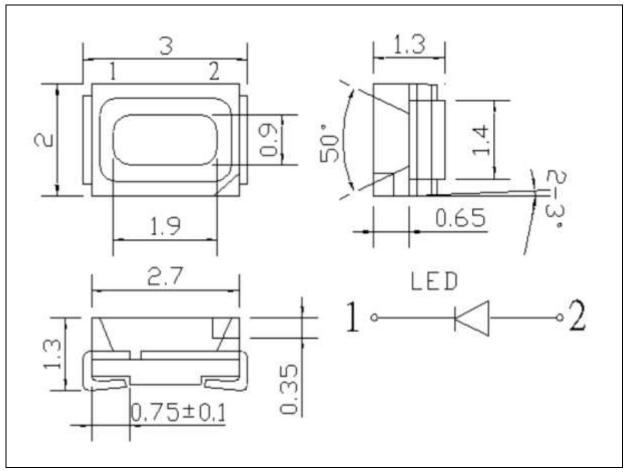
Parameter	Symbol	Values			Unit	Test
	Зуппоп	Min.	Тур.	Max.	Offic	Condition
Forward Voltage	V _F	1.7	2.0	2.5	V	I _F =20mA
Luminous Intensity	I _V	600	800		mcd	I _F =20mA
Dominant Wavelength	λ_{D}	585		597	nm	I _F =20mA
Viewing Angle	2θ _{1/2}		120		deg	I _F =20mA

^{1.} Luminous intensity (I_V) ±10%, Forward Voltage (V_F) ±0.1V.



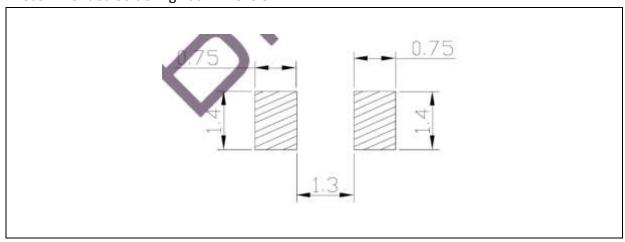
OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ±0.1mm with angle tolerance ±0.5°.



BINNING GROUPS:

Forward Voltage Classifications (I_F = 20mA):

Code	Min.	Max.	Unit
А	1.7	1.8	
В	1.8	1.9	
С	1.9	2.0	
D	2.0	2.1	V
E	2.1	2.2	V
F	2.2	2.3	
G	2.3	2.4	
Н	2.4	2.5	

Luminous Intensity Classifications (I_F = 20mA):

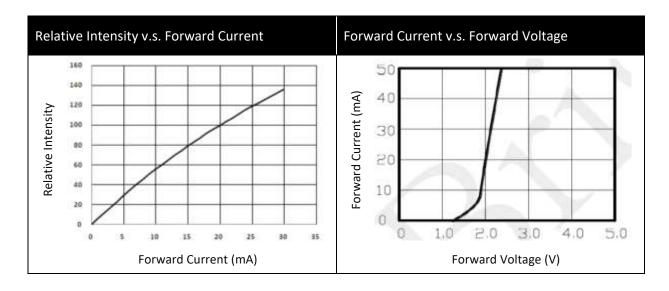
Code	Min.	Max.	Unit
13	600	780	
14	780	1000	mcd
15	1000	1300	

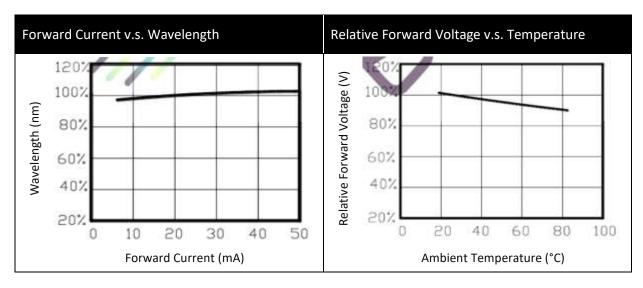
Dominant Wavelength Classifications (I_F = 20mA):

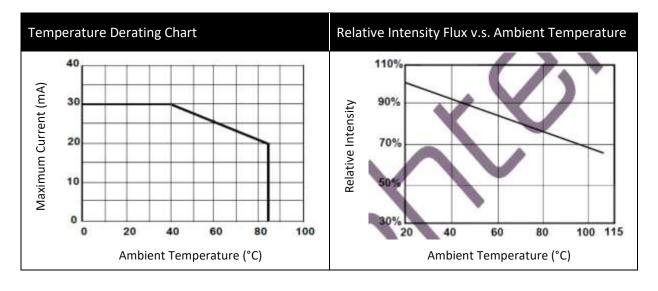
Code	Min.	Max.	Unit
С	585	588	
D	588	591	
E	591	594	nm
F	594	597	



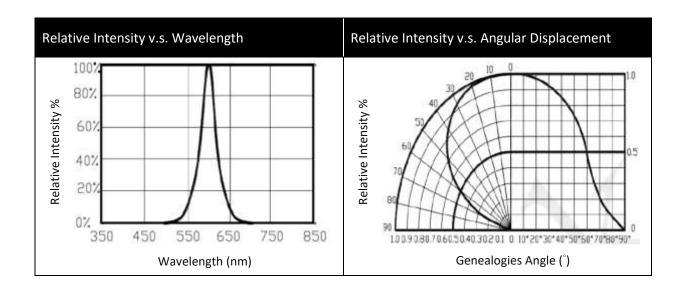
ELECTRO-OPTICAL CHARACTERISTICS:







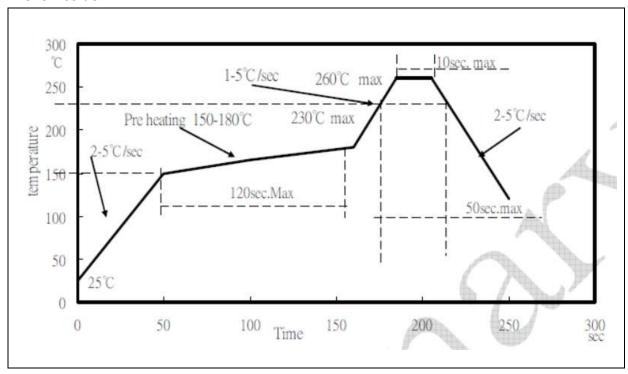






RECOMMENDED SOLDERING PROFILE:

Reflow solder:



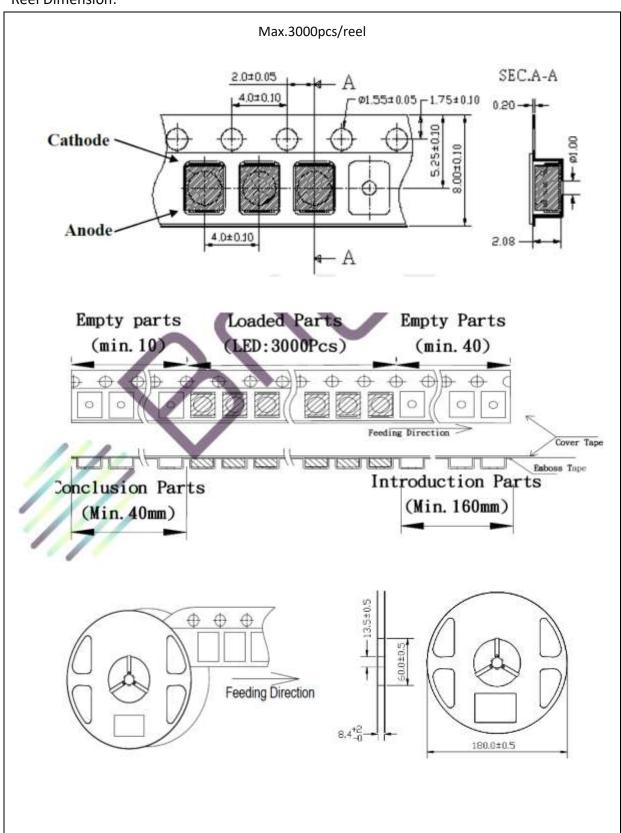
Note:

- 1. Recommend reflow temperature 240°C. The maximum soldering temperature should be limited to 260°C.
- 2. Maximum reflow soldering: 3 times.
- 3. Before, during, and after soldering, should not apply stress on the components and PCB board.



PACKING SPECIFICATION:

Reel Dimension:





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within 4 weeks. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

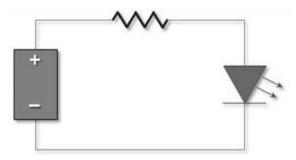
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 60±3°C x 6hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	27/07/2016	Datasheet set-up.
A1.1	29/05/2022	New datasheet format.